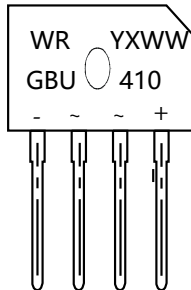


Ultrasoft Recovery Bridge



PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

Features

- Glass Passivated Chip Junction
- Reverse Voltage - 1000 V
- Forward Current - 4A
- High Surge Current Capability
- Designed For Surface Mount Application

Benefits

- Case: GBU
- Terminals: Solderable Per MIL-STD-750

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

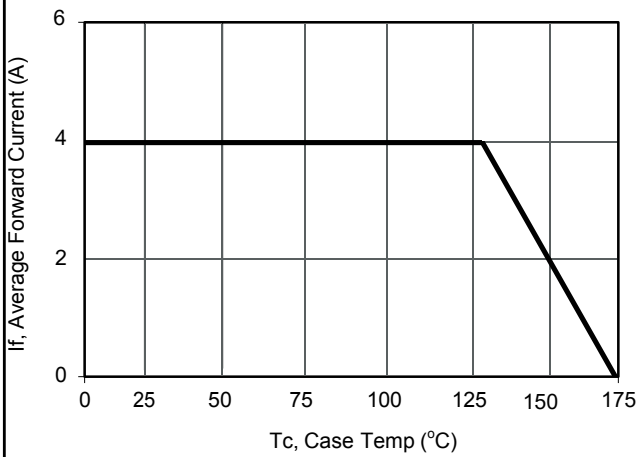
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	WRGBU410	Units
Maximum Repetitive Peak Reverse Voltage	VRRM	1000	V
Maximum RMS voltage	VRMS	700	V
Maximum DC Blocking Voltage	VDC	1000	V
Average Rectified Output Current	I _o	4.0	A
Reverse Recovery Time. IF=0.5A,IR=1A,IRR=0.25A	T _{rr}	10	us
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	110	A
I ² t rating for fusing (1ms< t < 10ms)	I ² t	60.5	A ² S
Maximum Forward Voltage at 2.0 A	V _F	1.0	V
Maximum DC Reverse Current @TA=25 °C at Rated DC Blocking Voltage @TA=125 °C	I _R	5 100	μA
Typical Junction Capacitance (Note1)	C _j	50	pF
Typical Thermal Resistance Junction to Ambient(Note 2)	R _{θJA}	26	°C/W
Typical Thermal Resistance Junction to Case(Note 2)	R _{θJC}	5.5	°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +175	°C

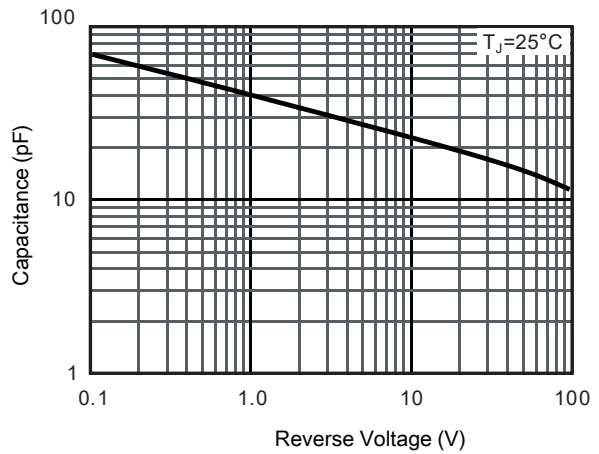
Note: 1. Measured at 1MHz and applied reverse voltage of 4 VDC.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

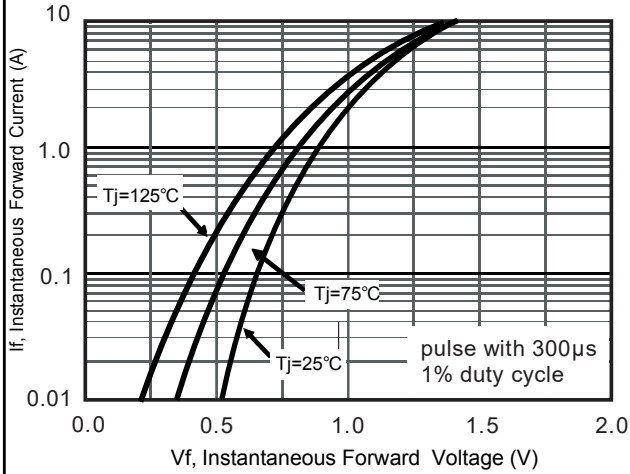
RATINGS AND CHARACTERISTICS CURVES (TA = 25 °C unless otherwise noted)



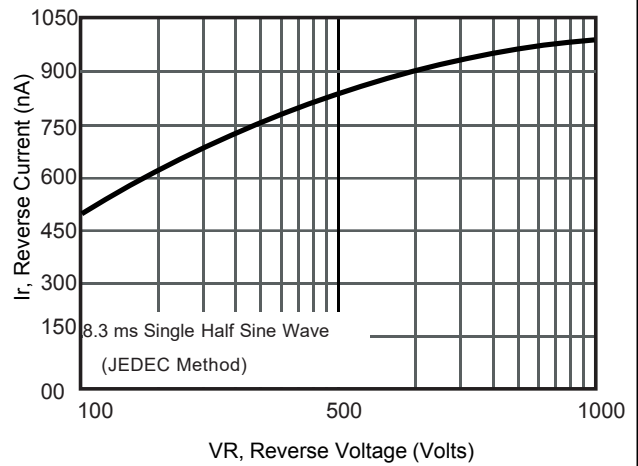
Current Derating, Case



Typical Junction Capacitance

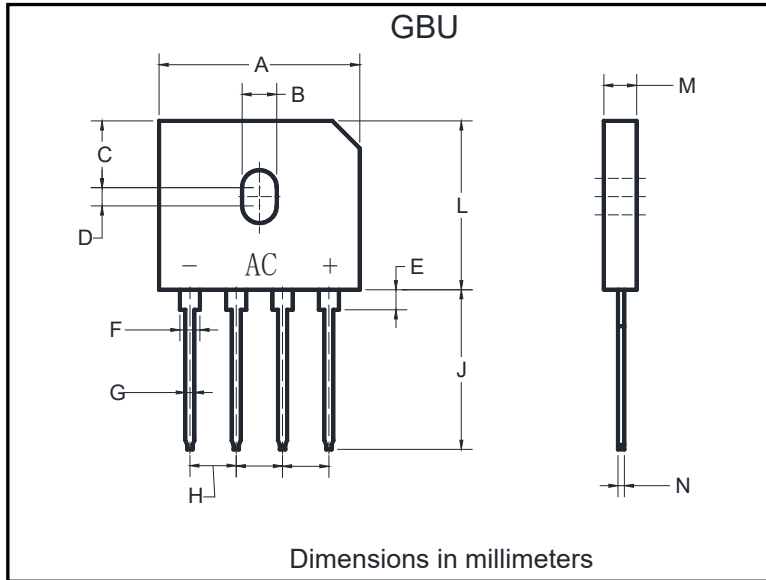


Typical Forward Voltage



Typical Reverse Current

PACKAGE OUTLINE DIMENSIONS



GBU		
Dim	Min	Max
A	21.80	22.30
B	3.50	4.10
C	7.40	7.90
D	1.65	2.16
E	2.25	2.75
F	2.05	2.3
G	1.02	1.27
H	4.83	5.33
J	17.0	18.5
L	18.3	18.8
M	3.30	3.56
N	0.46	0.56

